

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	10/538409	US-PGPUB; USPAT	ADJ	ON	2008/03/10 14:58
S2	2	("20030019027"   "6294063").PN.	US-PGPUB; USPAT	ADJ	ON	2008/03/10 14:58
S3	3	"2373095"	EPO; JPO; DERWENT	ADJ	ON	2008/03/10 15:34
S5	1	"6838361".pn.	US-PGPUB; USPAT	ADJ	ON	2008/03/10 15:36
S6	4	("6087196").PN. OR ("6838361").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/10 15:36
S7	18	("20010001050"   "20020197394"   "20030059975"   "20030059984"   "20030059987"   "20030060038"   "20030141810"   "5435887"   "6048573"   "6066357"   "6087196"   "6277679"   "6440877"   "6566153"   "6575800"   "6576975"   "6838361"   "6930322").PN. OR ("7067841").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/10 15:38
S8	1	"20030190278"	US-PGPUB; USPAT	ADJ	ON	2008/03/10 15:40
S9	1	("6712864").PN.	US-PGPUB; USPAT	ADJ	ON	2008/03/10 15:41
S10	58	"105876"	EPO; JPO; DERWENT	ADJ	ON	2008/03/10 15:44
S11	459	silicon dies	US-PGPUB; USPAT	ADJ	ON	2008/03/10 15:55
S12	374	silicon dies and substrate	US-PGPUB; USPAT	ADJ	ON	2008/03/10 15:55
S13	47	silicon dies and substrate and droplets	US-PGPUB; USPAT	ADJ	ON	2008/03/10 15:56
S14	206	silicon dies and substrate and fabrication	US-PGPUB; USPAT	ADJ	ON	2008/03/10 15:59
S15	36	duineveld, paulus.in.	US-PGPUB; USPAT	ADJ	ON	2008/03/10 16:16

S16	17	decre, michel.in.	US-PGPUB; USPAT	ADJ	ON	2008/03/10 16:22
S17	46	prins, menno.in.	US-PGPUB; USPAT	ADJ	ON	2008/03/10 16:29
S18	12948	mov\$5 same evaporation	US-PGPUB; USPAT	ADJ	ON	2008/03/10 16:30
S19	4486	mov\$5 with evaporation	US-PGPUB; USPAT	ADJ	ON	2008/03/10 16:31
S20	2179	422/99.ccls.	US-PGPUB; USPAT	ADJ	ON	2008/03/10 16:31
S22	811	438/478.ccls.	US-PGPUB; USPAT	ADJ	ON	2008/03/10 16:32
S23	201	droplet and evaporation and substrate	EPO; JPO; DERWENT	ADJ	ON	2008/03/10 18:17
S24	1	evaporat\$3 with movement and silicon dies	US-PGPUB; USPAT	ADJ	ON	2008/03/11 07:03
S25	5	evaporat\$3 with mov\$5 and silicon dies	US-PGPUB; USPAT	ADJ	ON	2008/03/11 07:04
S26	3232	evaporat\$3 with mov\$5 and substrate	US-PGPUB; USPAT	ADJ	ON	2008/03/11 07:05
S27	29	evaporat\$3 with mov\$5 and substrate and deflection with droplet	US-PGPUB; USPAT	ADJ	ON	2008/03/11 07:06
S28	349	evaporat\$3 with mov\$5 and substrate and meniscus	US-PGPUB; USPAT	ADJ	ON	2008/03/11 07:09
S29	1	438/478.ccls. and silicon dies	US-PGPUB; USPAT	ADJ	ON	2008/03/11 07:52
S30	43	ink jet and silicon dies	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/11 08:09
S31	243	73/863.ccls.	US-PGPUB; USPAT	ADJ	ON	2008/03/11 08:11
S32	1423	257/E21.705.ccls.	US-PGPUB; USPAT	ADJ	ON	2008/03/11 08:14
S33	5	257/E21.705.ccls. and silicon dies	US-PGPUB; USPAT	ADJ	ON	2008/03/11 08:15
S34	58	257/E21.705.ccls. and droplet	US-PGPUB; USPAT	ADJ	ON	2008/03/11 08:17
S35	26	257/E21.705.ccls. and droplet and (dice or die or dies)	US-PGPUB; USPAT	ADJ	ON	2008/03/11 08:31
S37	1	73/863.ccls. and droplet and (dice or die or dies)	US-PGPUB; USPAT	ADJ	ON	2008/03/11 08:38

S38	4	438/478.ccls. and droplet and (dice or die or dies)	US-PGPUB; USPAT	ADJ	ON	2008/03/11 08:38
S39	13	("20020037481"   "20030146019"   "2297691"   "4411735"   "4804600"   "4942110"   "5147397"   "5171650"   "5685939"   "5997677"   "6274508"   "6291126").PN. OR ("7217334").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/11 08:39
S40	19	422/99.ccls. and droplet and (dice or die or dies)	US-PGPUB; USPAT	ADJ	ON	2008/03/11 08:41
S41	3728	ink jet and droplet and (dice or die or dies)	US-PGPUB; USPAT	ADJ	ON	2008/03/11 08:46
S42	2928	ink jet and droplet and (dice or die or dies) and substrate	US-PGPUB; USPAT	ADJ	ON	2008/03/11 08:46
S43	1184	ink jet and droplet and (dice or die or dies) and substrate and evaporat\$3	US-PGPUB; USPAT	ADJ	ON	2008/03/11 08:47
S44	1061	S43 and place\$4	US-PGPUB; USPAT	ADJ	ON	2008/03/11 08:47
S45	362	S43 and placement	US-PGPUB; USPAT	ADJ	ON	2008/03/11 08:48
S46	12	ink jet and droplet and (dice or die or dies) and substrate and evaporation with movement	US-PGPUB; USPAT	ADJ	ON	2008/03/11 08:49
S47	1	"20010031514".pn.	US-PGPUB; USPAT	ADJ	ON	2008/03/11 09:00
S48	4	bock, karlheinz.in.	US-PGPUB; USPAT	ADJ	ON	2008/03/11 09:02
S49	6	("20010031514"   "20040115344"   "20060057293"   "6527964"   "6731353"   "6946322").PN. OR ("7195714").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/11 09:02
S50	6	bock, karlheinz.in.	EPO; JPO; DERWENT	ADJ	ON	2008/03/11 09:06
S53	955	438/691.ccls.	US-PGPUB; USPAT	ADJ	ON	2008/03/11 09:32

S54	5	438/691.ccls. and ink jet	US-PGPUB; USPAT	ADJ	ON	2008/03/11 09:32
S55	7	438/691.ccls. and droplet and (dice or die or dies)	US-PGPUB; USPAT	ADJ	ON	2008/03/11 09:35
S56	1	"5355577".pn.	US-PGPUB; USPAT	ADJ	ON	2008/03/11 09:39
S57	1	"6300149".pn.	US-PGPUB; USPAT	ADJ	ON	2008/03/11 09:41
S58	2222	substrate and placement	EPO; JPO; DERWENT	ADJ	ON	2008/03/11 09:47
S59	36	substrate and placement and ink jet	EPO; JPO; DERWENT	ADJ	ON	2008/03/11 09:47
S60	416	(dice or die or dies) with droplet	US-PGPUB; USPAT	ADJ	ON	2008/03/11 09:51
S61	224	(dice or die or dies) with droplet and substrate	US-PGPUB; USPAT	ADJ	ON	2008/03/11 09:52
S62	68	(dice or die or dies) with droplet and substrate and placement	US-PGPUB; USPAT	ADJ	ON	2008/03/11 09:52
S63	1750	die carrier	US-PGPUB; USPAT	ADJ	ON	2008/03/11 11:15
S64	1191	die carrier and substrate	US-PGPUB; USPAT	ADJ	ON	2008/03/11 11:15
S65	56	die carrier and substrate and evaporation and placement	US-PGPUB; USPAT	ADJ	ON	2008/03/11 11:16
S69	8	die with droplet and substrate and evaporation and placement	US-PGPUB; USPAT	ADJ	ON	2008/03/11 11:20
S70	161	die with liquid and substrate and evaporation and placement	US-PGPUB; USPAT	ADJ	ON	2008/03/11 11:23
S71	49	droplet and die and substrate	EPO; JPO; DERWENT	ADJ	ON	2008/03/11 11:34
S72	1073	die with suspension	US-PGPUB; USPAT	ADJ	ON	2008/03/11 11:38
S73	380	die with suspension and substrate	US-PGPUB; USPAT	ADJ	ON	2008/03/11 11:38
S74	641	movement and drop\$3 with die and substrate	US-PGPUB; USPAT	ADJ	ON	2008/03/11 11:45

S75	403	movement and drop\$3 with die and substrate and (dry\$3 or evaporat \$3)	US-PGPUB; USPAT	ADJ	ON	2008/03/11 11:45
S76	272	movement and drop\$3 with die and substrate and (dry\$3 or evaporat \$3) and ink\$4	US-PGPUB; USPAT	ADJ	ON	2008/03/11 11:45
S77	6	10/645389	US-PGPUB; USPAT	ADJ	ON	2008/03/11 11:52
S78	3	"2002358027"	EPO; JPO; DERWENT	ADJ	ON	2008/03/11 11:59
S79	4	"2001086639"	EPO; JPO; DERWENT	ADJ	ON	2008/03/11 11:59
S80	8	FRAUNHOFER-GESELLSCHAFT.as.	EPO; JPO; DERWENT	ADJ	ON	2008/03/11 12:03
S81	936	FRAUNHOFER-GESELLSCHAFT.as.	US-PGPUB; USPAT	ADJ	ON	2008/03/11 12:04
S82	352	FRAUNHOFER-GESELLSCHAFT.as. and substrate	US-PGPUB; USPAT	ADJ	ON	2008/03/11 12:04
S83	29	FRAUNHOFER-GESELLSCHAFT.as. and substrate and die	US-PGPUB; USPAT	ADJ	ON	2008/03/11 12:04
S84	7109	suspension and substrate and evaporation and placement	US-PGPUB; USPAT	ADJ	ON	2008/03/11 12:09
S85	32	suspension and substrate and evaporation with placement	US-PGPUB; USPAT	ADJ	ON	2008/03/11 12:09
S86	4695	print\$3 and die and droplet and substrate	US-PGPUB; USPAT	ADJ	ON	2008/03/11 12:19
S87	147	print\$3 and die with droplet and substrate	US-PGPUB; USPAT	ADJ	ON	2008/03/11 12:20
S88	6700	print\$3 and (element or component) with droplet and substrate	US-PGPUB; USPAT	ADJ	ON	2008/03/11 12:23
S89	1277	print\$3 and (element or component) with droplet with substrate	US-PGPUB; USPAT	ADJ	ON	2008/03/11 12:23
S90	267	print\$3 and (element or component) with droplet with substrate and placement	US-PGPUB; USPAT	ADJ	ON	2008/03/11 12:23
S91	17983	H01L021/302	EPO; JPO; DERWENT	ADJ	ON	2008/03/11 12:51

S92	8415	H01L021/302 and substrate	EPO; JPO; DERWENT	ADJ	ON	2008/03/11 12:51
S93	54	H01L021/302 and substrate and drop\$3	EPO; JPO; DERWENT	ADJ	ON	2008/03/11 12:51
S94	0	H01L021/461 and substrate and drop\$3	EPO; JPO; DERWENT	ADJ	ON	2008/03/11 12:56
S95	77	H01L021/461	EPO; JPO; DERWENT	ADJ	ON	2008/03/11 12:56
S96	1	"20040029382".pn.	US-PGPUB; USPAT	ADJ	ON	2008/03/11 13:22
S97	51	pick place die	US-PGPUB; USPAT	ADJ	ON	2008/03/11 13:44
S98	7	micro-contacting	US-PGPUB; USPAT	ADJ	ON	2008/03/11 13:51
S99	731	micro-contact\$3	US-PGPUB; USPAT	ADJ	ON	2008/03/11 13:52
S100	483	micro-contact\$3 printing	US-PGPUB; USPAT	ADJ	ON	2008/03/11 13:52
S101	135	micro-contact\$3 printing and substrate and droplet	US-PGPUB; USPAT	ADJ	ON	2008/03/11 13:53
S102	388	fluidic self assembly	US-PGPUB; USPAT	ADJ	ON	2008/03/11 14:06
S103	373	fluidic self assembly and substrate	US-PGPUB; USPAT	ADJ	ON	2008/03/11 14:06
S104	20	fluidic self assembly and substrate and droplet	US-PGPUB; USPAT	ADJ	ON	2008/03/11 14:06
S105	6	"989778"	EPO; JPO; DERWENT	ADJ	ON	2008/03/12 06:47
S106	1	("6087196").PN.	US-PGPUB; USPAT	ADJ	ON	2008/03/12 06:50
S107	127	("4736704"   "5132248"   "5250439"   "5312654"   "5385848"   "5495250"   "5880176"   "5919532").PN. OR ("6087196").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/12 06:50
S108	2579	evaporation deposition	US-PGPUB; USPAT	ADJ	ON	2008/03/12 06:56
S109	0	evaporation deposition and droplet and packet	US-PGPUB; USPAT	ADJ	ON	2008/03/12 06:56
S110	433	placement and droplet and packet	US-PGPUB; USPAT	ADJ	ON	2008/03/12 06:56
S111	315	placement and droplet and packet and substrate	US-PGPUB; USPAT	ADJ	ON	2008/03/12 06:56

S112	23	align\$4 and droplet with packet and substrate	US-PGPUB; USPAT	ADJ	ON	2008/03/12 06:59
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